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A LOOK AT THE LATEST IN TEST & INSPECTION TECHNOLOGY FROM TRI

Meet TRI's 3D X-Ray Solution: The TR7600 SII AXI

- High speed inline 3D X-Ray inspection
- Tomosynthesis 3D imaging technology
- High resolution mode for 01005 components
- Multi-resolution programs for optimal inspection performance and speed
- Max Board Size: 900 x 460 mm (TR7600LL SII up to 1000 x 660 mm)
- Specialized Pressfit, PoP, PTH & BTC algorithms

TRI's advanced inline automated 3D X-ray inspection system is built for fast, accurate inspection of visible and hidden solder joints on both sides of a PBCA, as well as components with array solder joints like BGAs, LGAs, CGAs, CSPs and flip-chips. Featuring TRI's dynamic imaging technology, the TR7600 SII system offers high inspection speeds and extensive defect coverage to achieve reliable inspection on both large and complex boards utilized in automotive, aerospace, communications, medical, smartphone and other industries with strenuous quality requirements. TRI's 3D X-ray inspection solution helps our customers deliver products with improved reliability in a cost-effective manner.

Smart Processing

The key component in analyzing and evaluating X-ray images is TRI's advanced image processing software with specialized algorithms for inspecting thru-hole (PTH), Pressfit, BTC and PoP components. Internally developed by TRI, this vital component ensures your AXI system will deliver state-of-art performance for years to come.

High Resolution Imaging

TRI features digital tomosynthesis technology (US Patent: 7,529,336 B2) combined with TR7600 SII software to provide different slice heights in one inspection cycle. With a market-leading selectable resolution (20 µm, 15 µm, 10µm and 7.5 µm) operators can optimize settings to find the ideal solution for inspection speed and accuracy. 3D AXI is able

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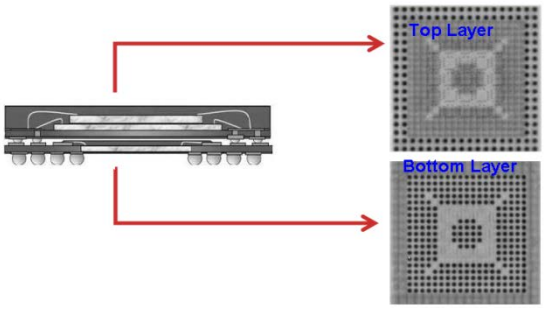
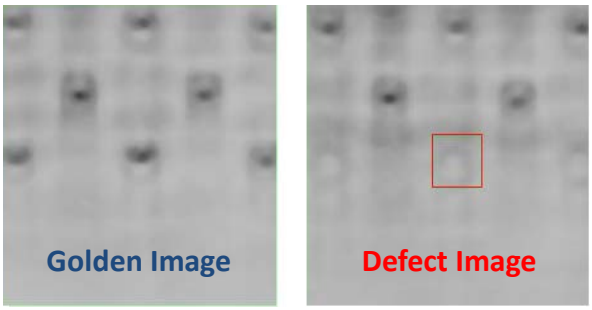
to test more joints and find a greater percentage of total known defects than any other independent methodology.

Advanced Block Scan Function

With the block scan function, the TR7600 SII allows the operator to modify existing inspection programs so that any area of a test board can be rescanned using different conditions such as resolution, power or current settings, and source/detector offset for inspecting 01005 chips, mirror BGAs, LGA voids and special connectors.



Clear PoP Stacked Die Inspection Using Multiple 3D Slices

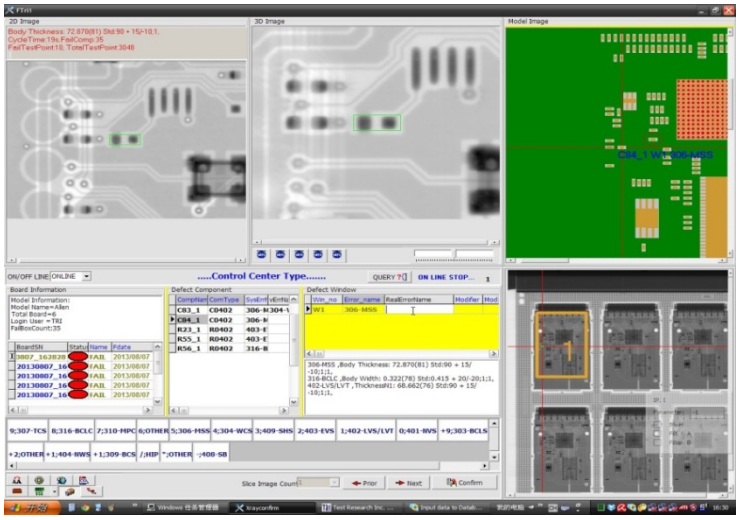


Pressfit Connector Barrels Visualized Using Block Scan

Statistical Analysis & Repair

The TR7600 SII's new Repair Station combines defect visualization functions with defect analytics for statistical process control and defect management.

The redesigned interface helps identify defects on panel map for multi-board panels and offers enhanced angle views for easier defect confirmation.



The New TR7600 SII Repair Station Interface

Easily identify components and pins using panel map locator.

About TRI

TRI offers the most robust product portfolio in the industry for automatic test and inspection solutions. From solder paste inspection, automated optical inspection and 3D automated X-ray inspection systems to manufacturing defect analyzers and in-circuit test equipment, TRI provides the most cost-effective solutions to meet a comprehensive range of manufacturing test and inspection requirements. Learn more at www.tri.com.tw. For sales and service information, write us at sales@tri.com.tw or call +886-2-2832-8918.